

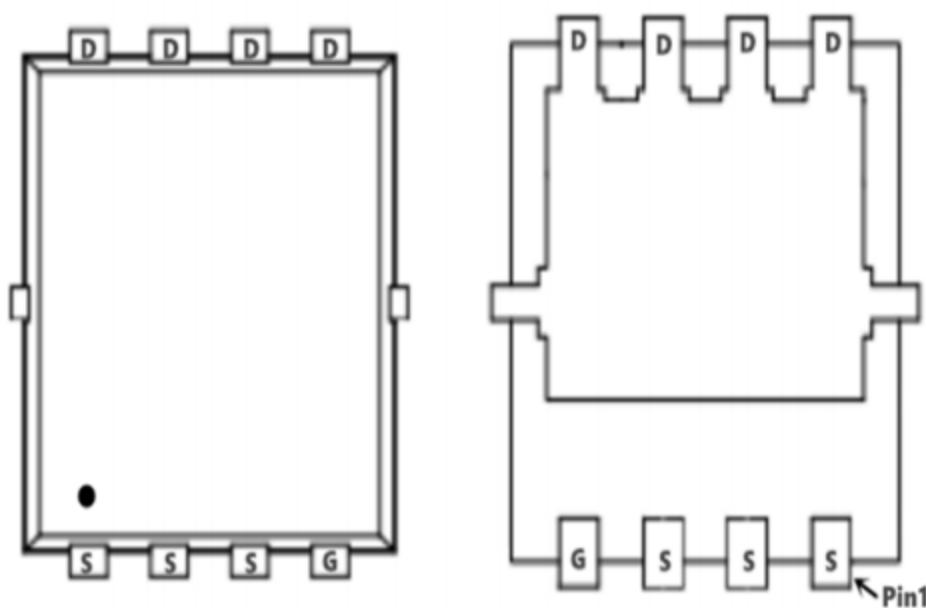
Product Summary

- $V_{DS} = 40V$
- $I_D = 60A (V_{GS} = 10V)$
- $R_{DS(ON)}=5.5\text{ m}\Omega @ V_{GS} =10V$
- $R_{DS(ON)}=6.0\text{ m}\Omega @ V_{GS} =4.5V$

Application

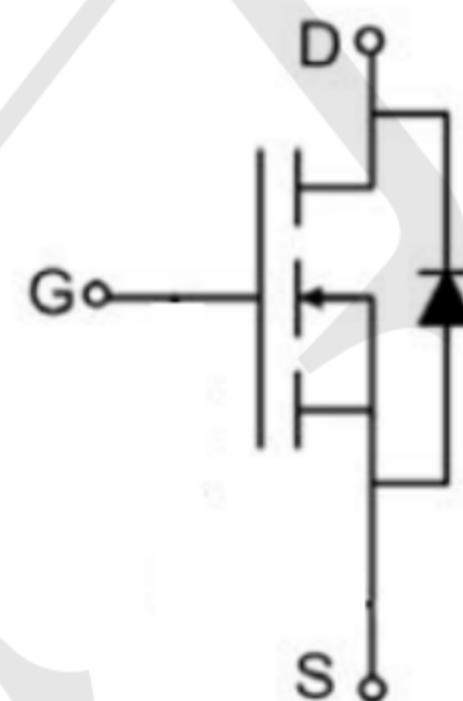
- Load Switch
- Power management in portable/desktop PCs
- DC/DC conversion

Package and Pin Configuration



PDFN5*6-8L

Circuit diagram



Marking:M4060N

Absolute Maximum Ratings ($T_A=25^\circ C$ unless otherwise specified)

Symbol	Parameter	Steady State	Units
V_{DS}	Drain-Source Voltage	40	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current ¹	$T_C = 25^\circ C$	A
I_{DM}	Pulsed Drain Current ²		A
I_S	Continuous Source Current (Diode Conduction) ¹	60	A
E_{AS}	Single Pulse Drain-Source Avalanche Energy ³	300	mJ
P_D	Maximum Power Dissipation	$T_A = 25^\circ C$	W
		$T_C = 25^\circ C$	
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55~150	°C

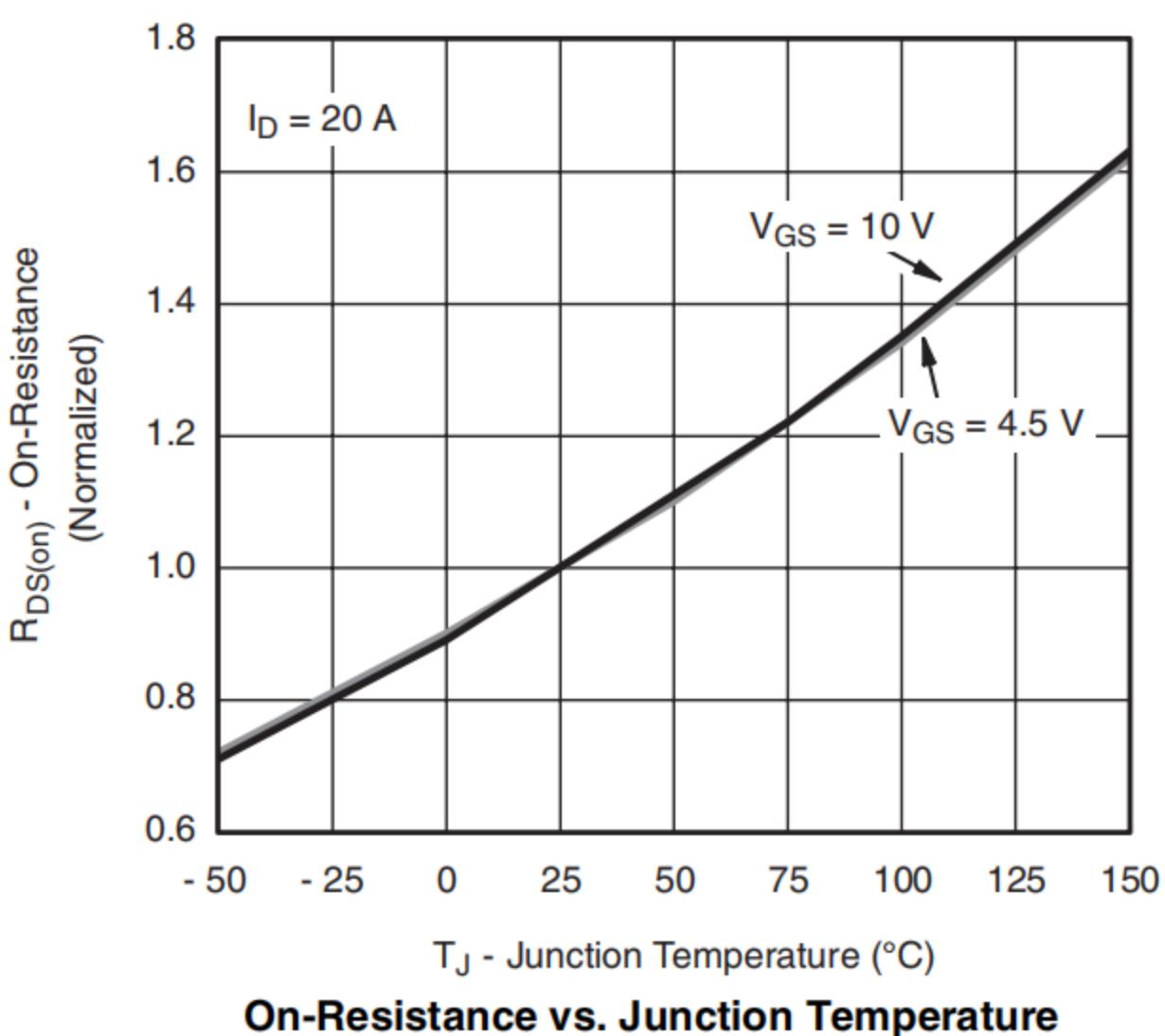
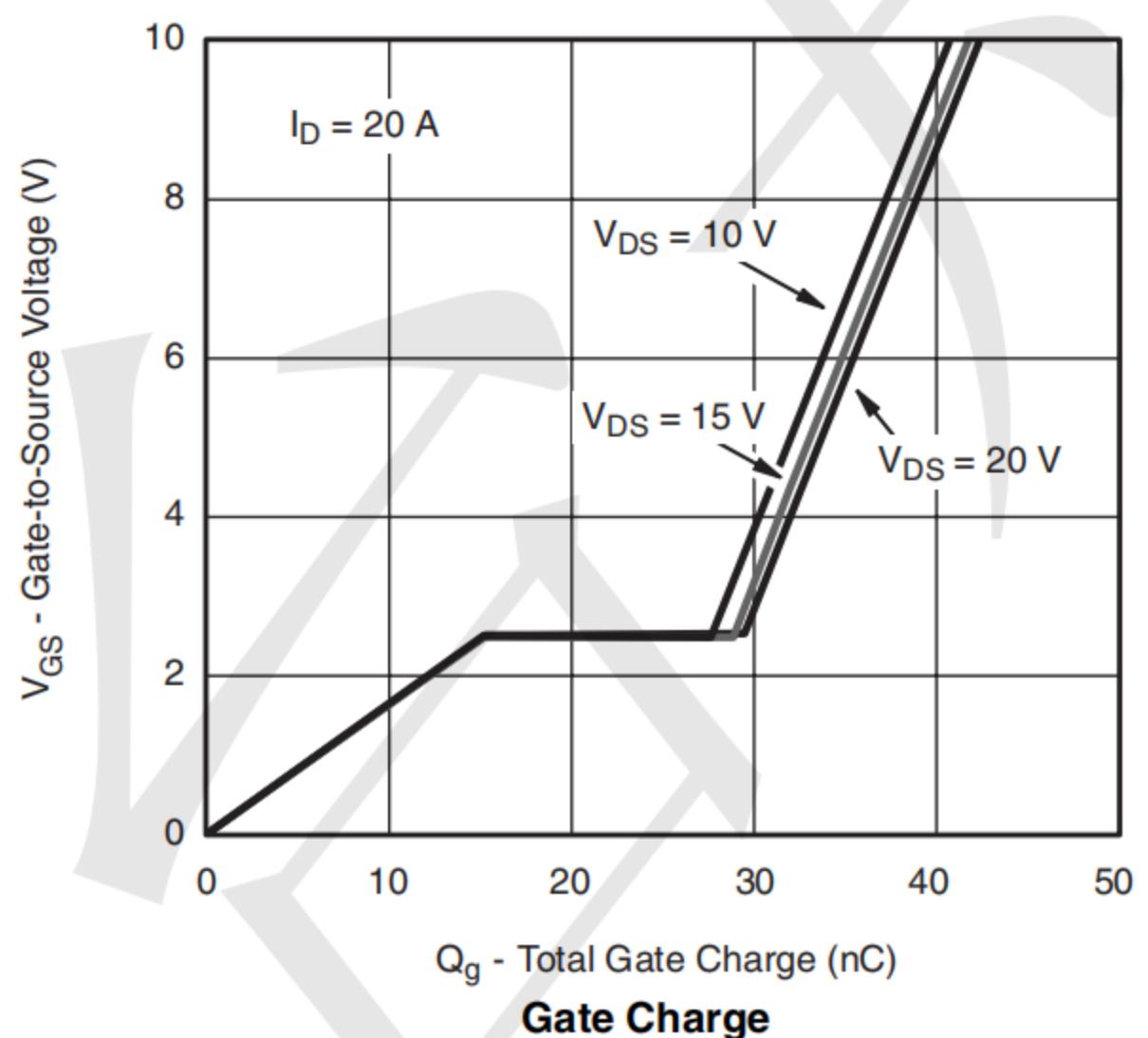
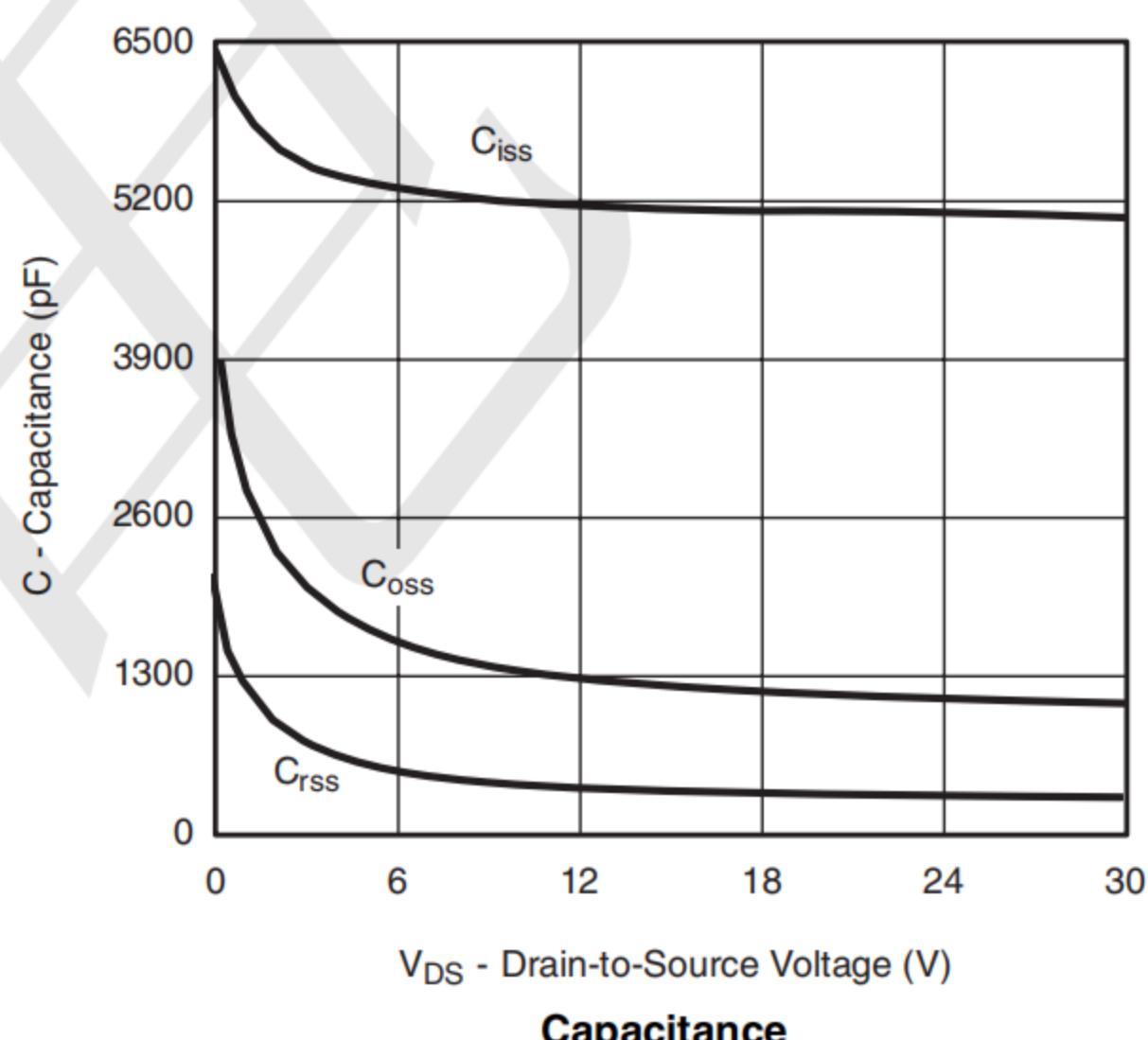
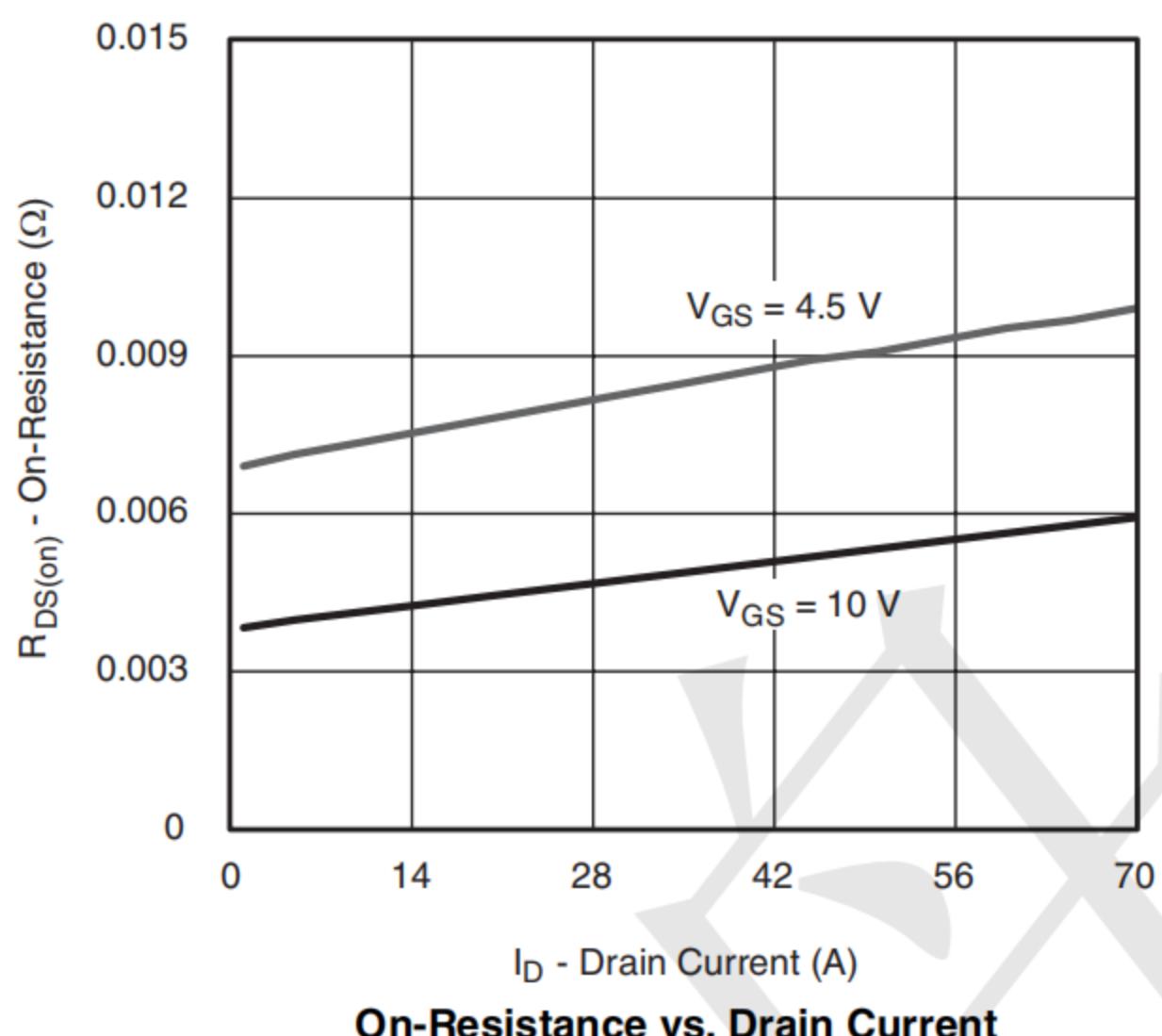
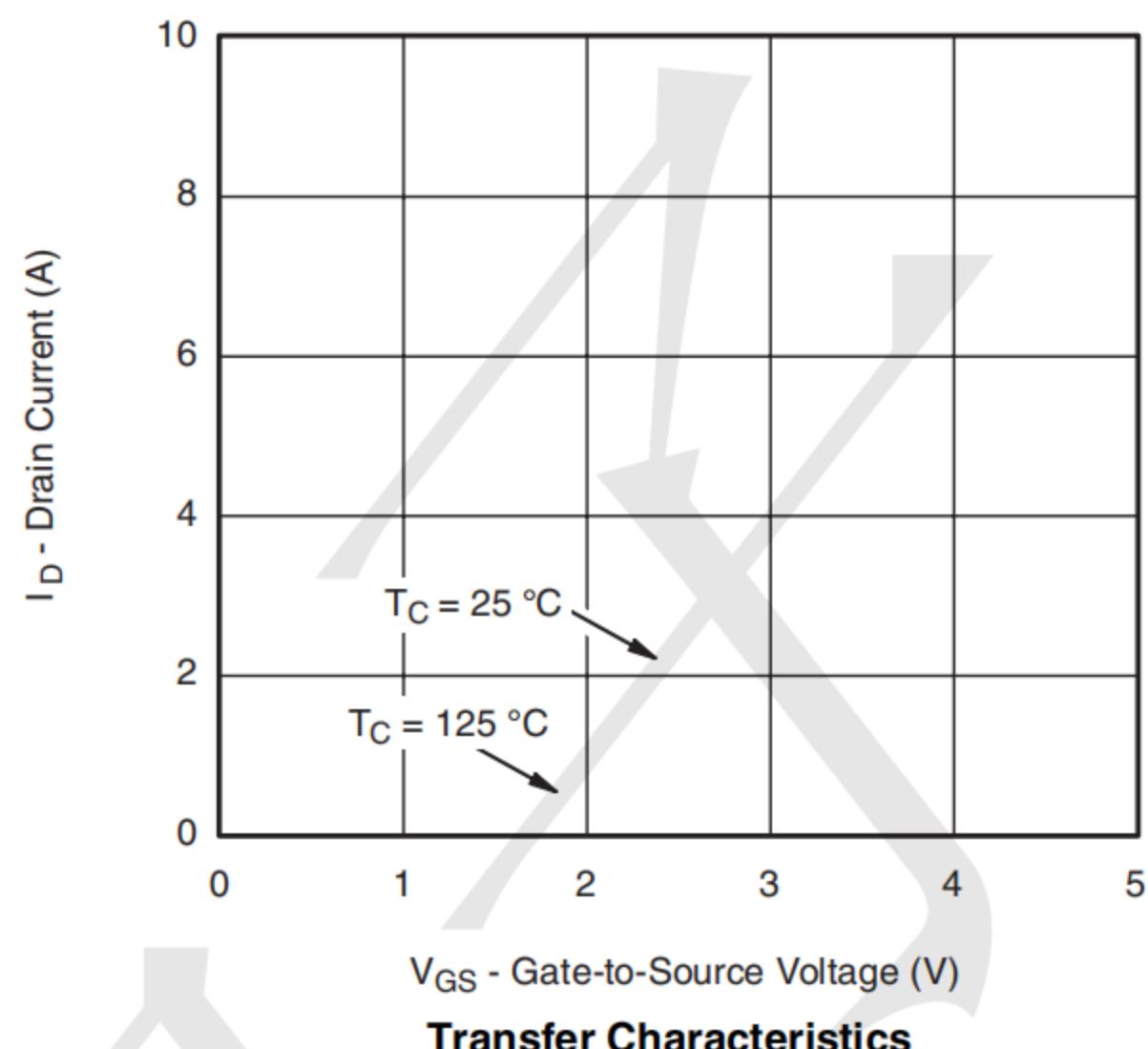
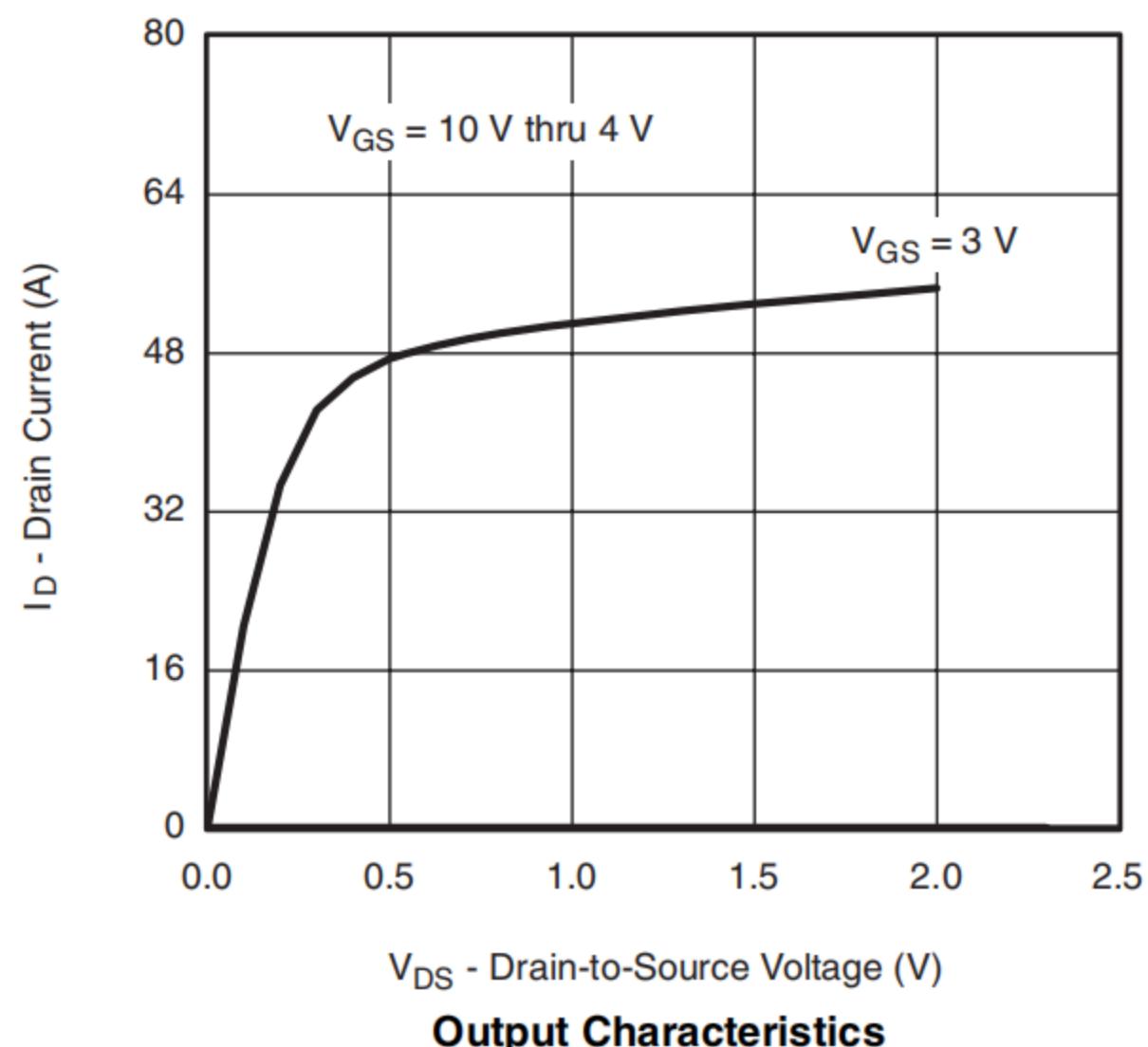
Thermal Characteristics

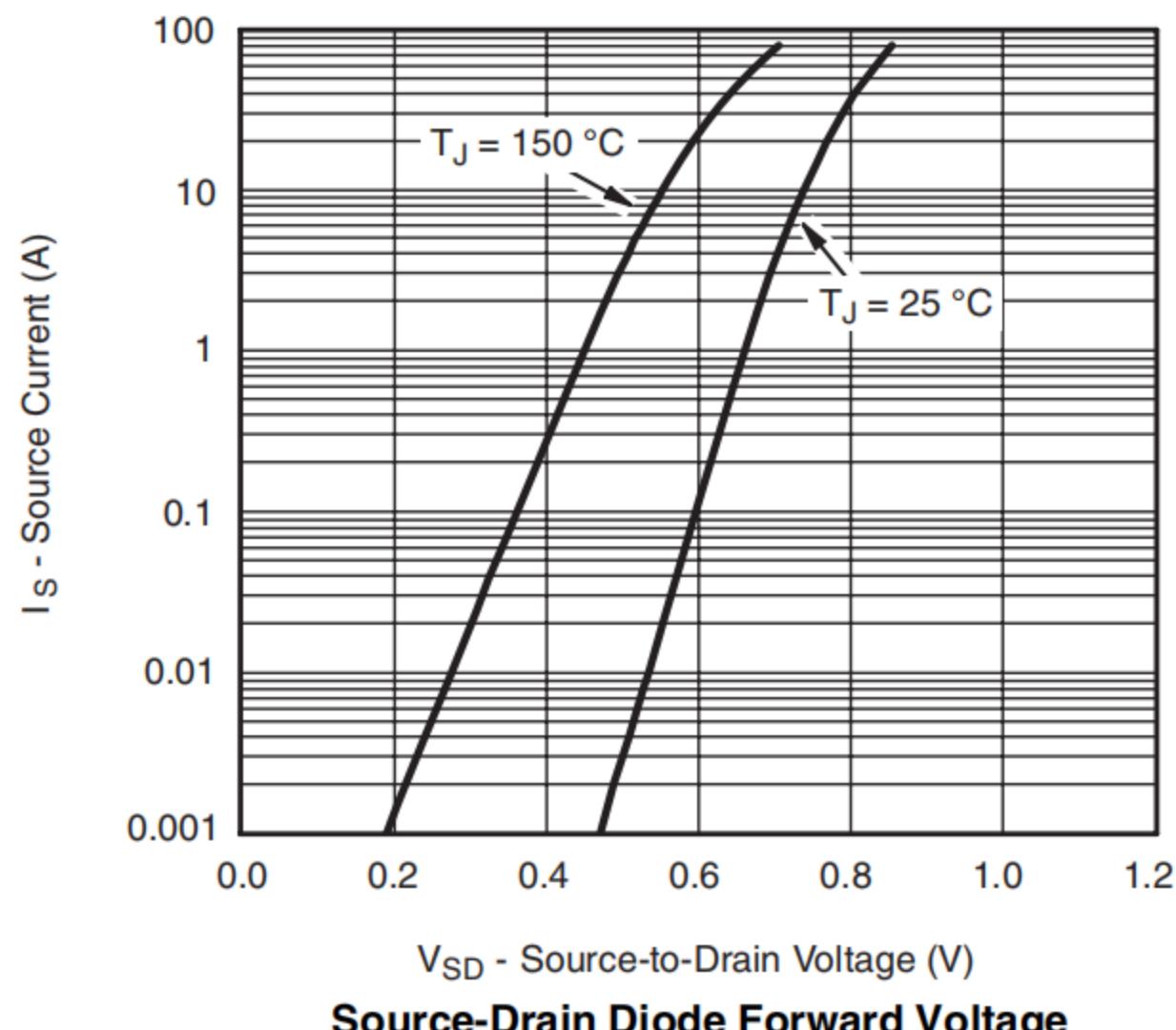
Symbol	Parameter	Typical	Maximum	Unit
R_{thJA}	Maximum Junction-to-Ambient	-	62.5	°C/W
R_{thJC}	Maximum Junction-to-Case	-	1.4	

Electrical Characteristics ($T = 25^\circ\text{C}$ unless otherwise specified)

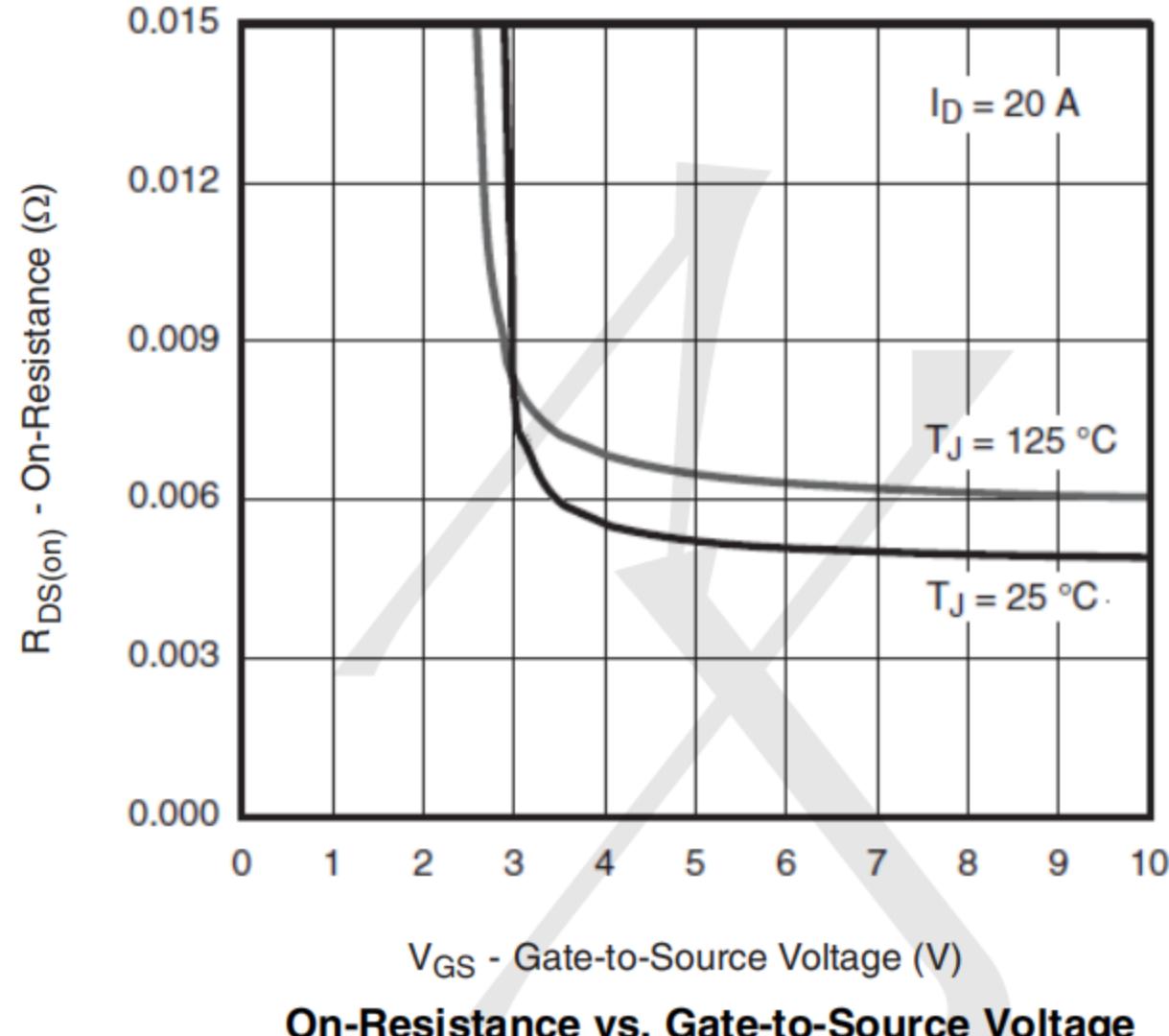
Symbol	Parameter	Test Condition	Min	Typ	Max	Unit
Static Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}} = 0\text{V}, I_{\text{D}} = 250\mu\text{A}$	40	-	-	V
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}} = V_{\text{DS}}, I_{\text{D}} = 250\mu\text{A}$	1	1.8	2.2	V
I_{GSS}	Gate-Body Leakage Current	$V_{\text{GS}} = \pm 20\text{V}, V_{\text{DS}} = 0\text{V}$	-	-	± 100	nA
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}} = 32\text{V}, V_{\text{GS}} = 0\text{V}$	-	1		μA
		$V_{\text{DS}} = 32\text{V}, V_{\text{GS}} = 0\text{V}, T_{\text{J}} = 85^\circ\text{C}$	-	30		
$R_{\text{DS(on)}}$	Drain Source On State Resistance ^a	$V_{\text{GS}} = 10\text{V}, I_{\text{D}} = 60\text{A}$	-	5.5	6.5	$\text{m}\Omega$
		$V_{\text{GS}} = 4.5\text{V}, I_{\text{D}} = 30\text{A}$	-	6.0	8.0	
V_{SD}	Diode Forward Voltage ^a	$V_{\text{GS}} = 0\text{V}, I_{\text{S}} = 40\text{A}$	-	0.82	1.3	V
Dynamic Characteristics ^b						
C_{iss}	Input Capacitance	$V_{\text{DS}} = 15\text{V}, V_{\text{GS}} = 0\text{V}, f = 1\text{MHz}$	-	5120	-	pF
C_{oss}	Output Capacitance		-	1210	-	
C_{rss}	Reverse Transfer Capacitance		-	390	-	
Q_{g}	Total Gate Charge	$V_{\text{DS}} = 15\text{V}, V_{\text{GS}} = 10\text{V}, I_{\text{D}} = 20\text{A}$	-	41	-	nC
Q_{gs}	Gate-Source Charge		-	15	-	
Q_{gd}	Gate-Drain Charge		-	12	-	
$t_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DD}} = 15\text{V}, V_{\text{GS}} = 4.5\text{V}$ $I_{\text{D}} = 20\text{A}, R_{\text{GEN}} = 3\Omega$	-	22	-	nSec
t_{r}	Rise Time		-	35	-	
$t_{\text{d(off)}}$	Turn-Off Delay Time		-	50	-	
t_{f}	Fall Time		-	27	-	
t_{rr}	Body Diode Reverse Recovery Time	$I_{\text{F}} = 20\text{A}, di/dt = 100\text{A}/\mu\text{A}, T_{\text{J}} = 25^\circ\text{C}$	-	33	-	nSec

Typical Electrical and Thermal Characteristic Curves

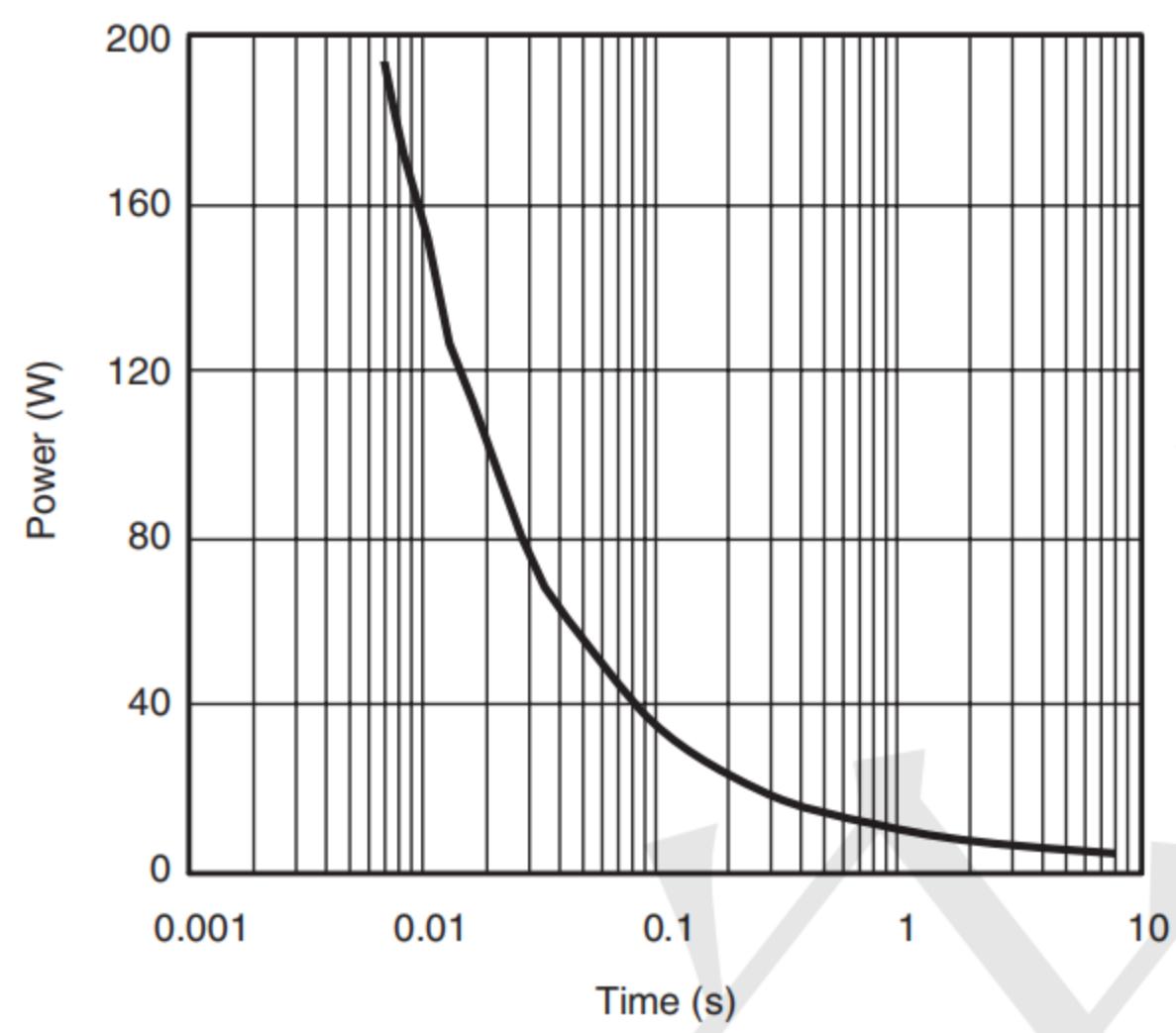




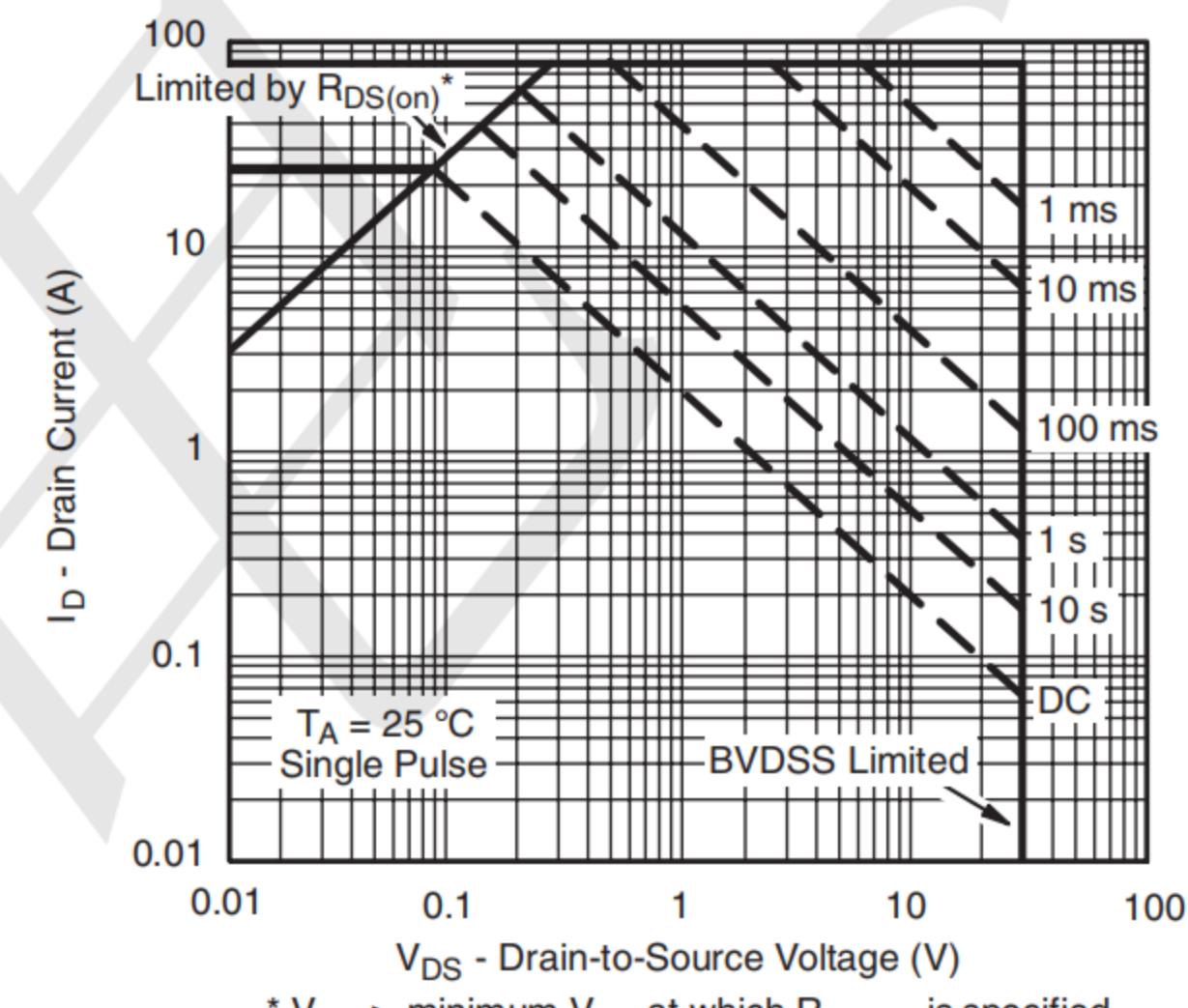
Source-Drain Diode Forward Voltage



On-Resistance vs. Gate-to-Source Voltage

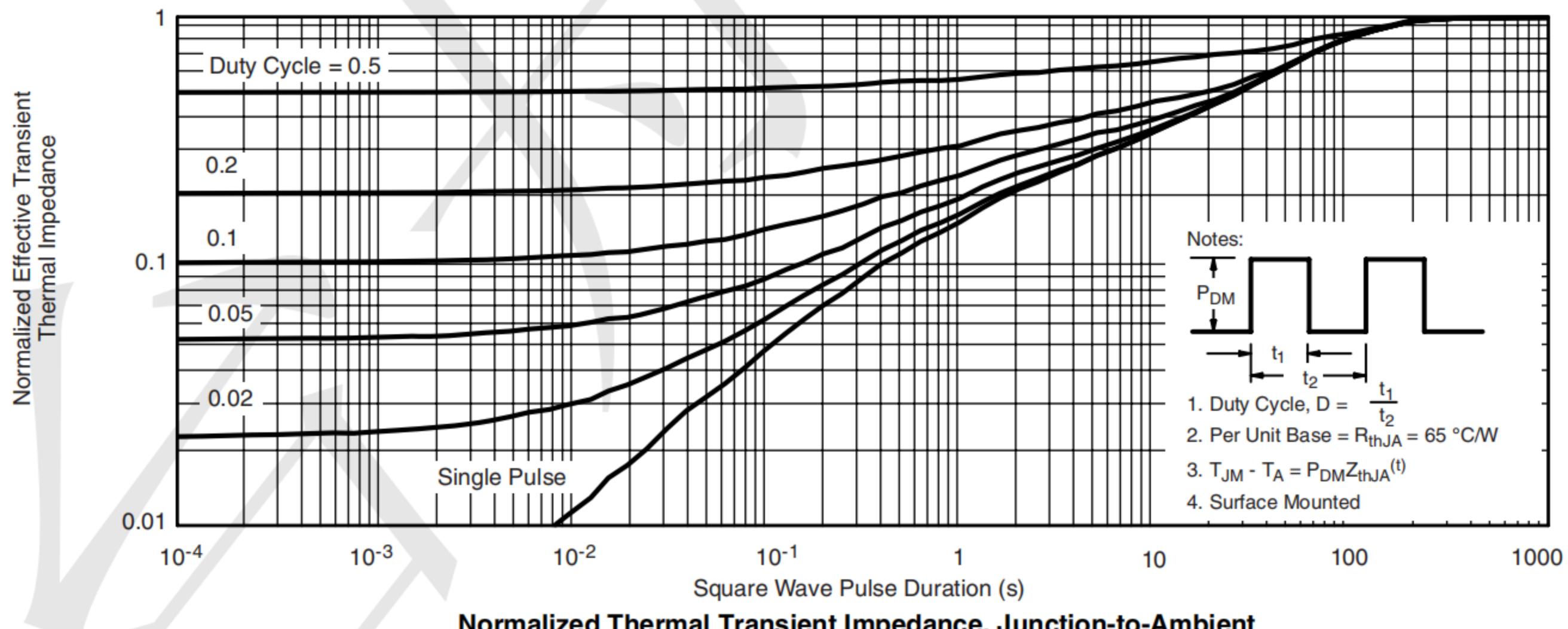


Single Pulse Power, Junction-to-Ambient



* $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified

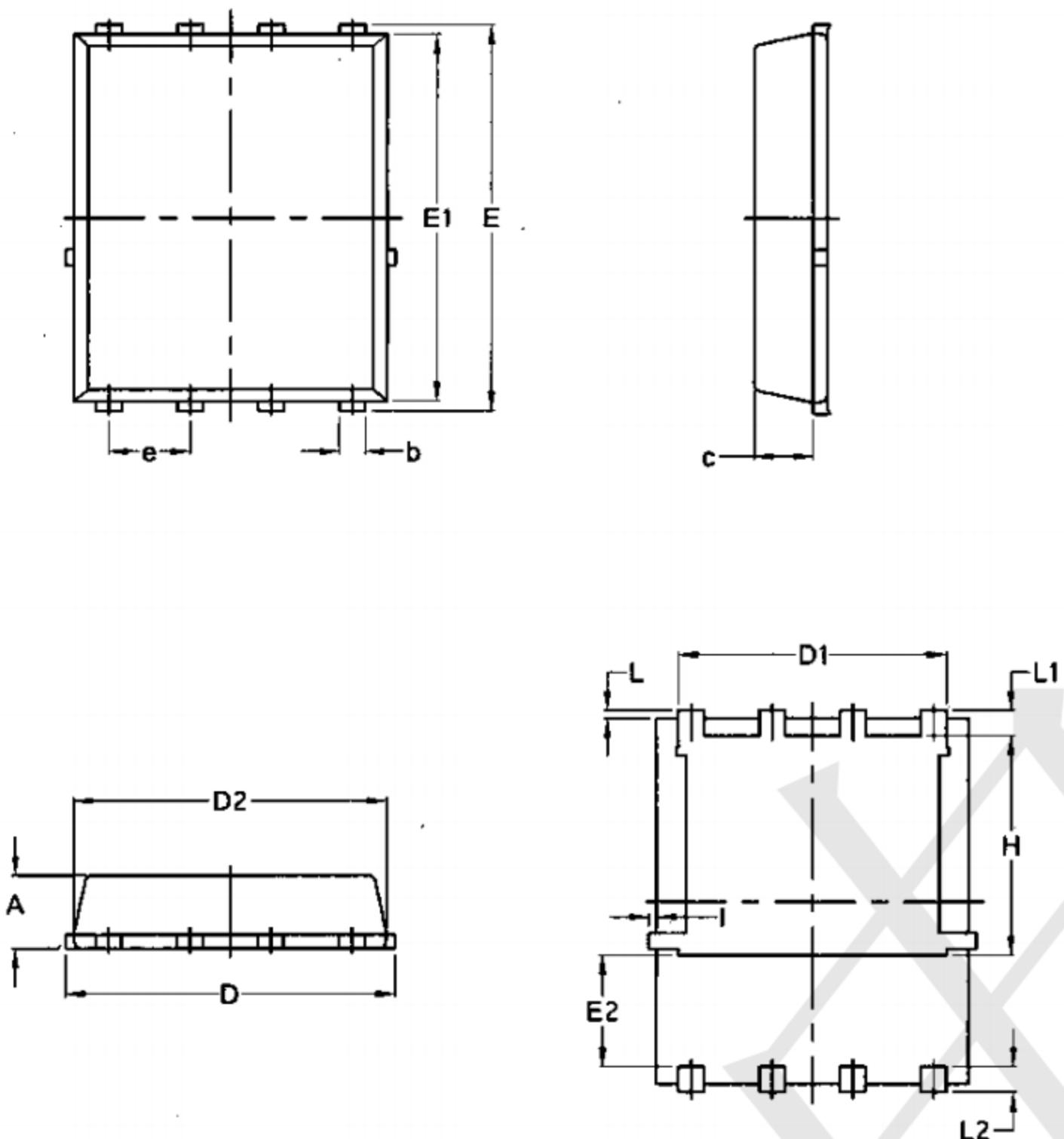
Safe Operating Area, Junction-to-Ambient



Notes:

- 1. Duty Cycle, $D = \frac{t_1}{t_1 + t_2}$
- 2. Per Unit Base = $R_{thJA} = 65^\circ\text{C/W}$
- 3. $T_{JM} - T_A = P_{DM}Z_{thJA}(t)$
- 4. Surface Mounted

Package Outline Dimensions PDFN5*6-8L



Symbol	Common			
	mm		Inch	
	Min	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070